

ABSTRACT

A method of forming a patterned thin film comprises the steps of forming a first plating layer and a second plating layer. Each of the steps of forming the plating layers includes: the step of forming a coating film by
5 applying a liquid resist to the layer below; the heat processing step of forming a resist layer by performing heat processing on the coating film; the step of forming a frame by patterning the resist layer; and the step of forming the plating layer by plating through the use of the frame. Each of sublayers includes: a first portion having a sidewall and encased in a groove of the
10 frame; and the second portion extending out of the groove. The second portion has overhang portions that overhang and extend more outward than the sidewall of the first portion.